IPC ASSOCIATION CONI ELECTRONICS INDI	Material Comp © Copyright 2005. international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and M	fg Informa	ition		
upplier Inf	formation														
Company nam	ne*	Company unique ID			ī	Unique ID Authority					Response Date*				
onsemi												2025-07-03			
Contact Name			Title - Contact				Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-Env-S	Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Rec	Requester Item Number Mfr It		Item Number Mfr Item Name				Effective Da	ite V	ersion	Manufacturing Site		1	Weight*	UOM	Unit Type
		ATP304-TL-H		PCH 4.5V DRIVE SERIES			2025-07-03	25-07-03			271.02		mg	Each	
Ianufactur	ring Proccess Informa	ation													
Terr	Terminal Plating / Grid Array Material			Terminal Base Alloy J-STD-020 M		L Rating	Peak Process J		s Body Temperature Max Time at Peak		Temperat	ure Num	ber of Reflow Cyc	eles	
contains Bi		CU Alloy 1			260		C	30		secon	ds 3				
omments															
vel 1 - maxim	num time at peak temperat	ture during sol	dering is 10-3	30 seconds											
or more infor	rmation regarding materia	l composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	10.29	mg	Supplier	Silicon (Si)	7440-21-3		10.29	mg
Die Attach Solder	8.6		Supplier	Silver (Ag)	7440-22-4		0.215	mg
			A	Lead (Pb)	7439-92-1	7a	7.955	mg
			Supplier	Tin (Sn)	7440-31-5		0.43	mg
Lead Frame	151.27		Supplier	Tin (Sn)	7440-31-5		0.2269	mg
			Supplier	Copper (Cu)	7440-50-8		151.0431	mg
Mold Compound-Black	97.56			Epoxy resin	proprietary data		4.878	mg
			Supplier	Phenolic Resin	Proprietary Data		0.9756	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		13.6584	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4878	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		77.5602	mg
Plating	3.3	mg	В	Bismuth (Bi)	7440-69-9		0.0198	mg
			Supplier	Tin (Sn)	7440-31-5		3.2802	mg